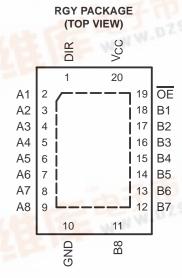
SCES271C - APRIL 1999 - REVISED SEPTEMBER 2003

- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 3.4 ns at 3.3 V

DGV, DW, NS, OR PW PACKAGE (TOP VIEW)



- ±24-mA Output Drive at 3.3 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17



description/ordering information

This octal bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVC245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKA	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-	QFN – RGY	Tape and reel	SN74ALVC245RGYR	VA245
	COIC DW	Tube	SN74ALVC245DW	ALV/0045
-40°C to 85°C	SOIC - DW	Tape and reel	SN74ALVC245DWR	ALVC245
	SOP - NS	Tape and reel	SN74ALVC245NSR	ALVC245
	T000D DW	Tube	SN74ALVC245PW	WALLS IN THE
	TSSOP – PW	Tape and reel	SN74ALVC245PWR	VA245
	TVSOP - DGV	Tape and reel	SN74ALVC245DGVR	VA245

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

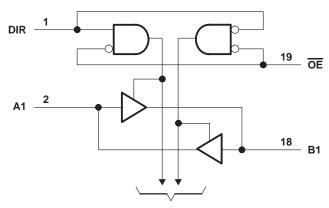
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FUNCTION TABLE

INP	UTS	ODED ATION			
OE	DIR	OPERATION			
L	L	B data to A bus			
L	Н	A data to B bus			
Н	Χ	Isolation			

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I : Except I/O ports (see Note 1)	0.5 V to 4.6 V
I/O ports (see Notes 1 and 2)	\dots -0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I _O	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DGV package	92°C/W
(see Note 3): DW package	58°C/W
(see Note 3): NS package	60°C/W
(see Note 3): PW package	83°C/W
(see Note 4): RGY package	37°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 4.6 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
 - 4. The package thermal impedance is calculated in accordance with JESD 51-5.



SN74ALVC245 OCTAL BUS TRANSCEIVER WITH 3-STATE OUTPUTS SCES271C - APRIL 1999 - REVISED SEPTEMBER 2003

recommended operating conditions (see Note 5)

			MIN	MAX	UNIT
VCC	Supply voltage		1.65	3.6	V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
۷ _{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V
		V _{CC} = 2.7 V to 3.6 V		0.8	
٧١	Input voltage	•	0	VCC	V
٧o	Output voltage		0	VCC	V
		V _{CC} = 1.65 V		-4	
		V _{CC} = 2.3 V		-12	
ЮН	High-level output current	V _{CC} = 2.7 V		-12	mA
		VCC = 3 V		1.7 2 0.35 × V _{CC} 0.7 0.8 0 V _{CC} 0 V _{CC} -4 -12	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		3.6 0.35 × V _{CC} 0.7 0.8 V _{CC} -4 -12 -12 -24 4 12 12 24 10	1.
loL	Low-level output current	V _{CC} = 2.7 V		12	mA
	$V_{CC} = 3 \text{ V}$			24	
Δt/Δν	Input transition rise or fall rate	•		10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN74ALVC245 **OCTAL BUS TRANSCEIVER** WITH 3-STATE OUTPUTS SCES271C - APRIL 1999 - REVISED SEPTEMBER 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST CO	ONDITIONS	VCC	MIN	TYP [†]	MAX	UNIT
		I _{OH} = -100 μA		1.65 V to 3.6 V	VCC-0	.2		
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2			
		I _{OH} = -6 mA		2.3 V	2			
∨он				2.3 V	1.7			V
		I _{OH} = -12 mA		2.7 V	2.2			
				3 V	2.4			
		I _{OH} = -24 mA		3 V	2			
		$I_{OL} = 100 \mu\text{A}$		1.65 V to 3.6 V			0.2	
		$I_{OL} = 4 \text{ mA}$		1.65 V			0.45	
.,		I _{OL} = 6 mA	2.3 V			0.4	V	
VOL		I _{OL} = 12 mA		2.3 V			0.7	V
				2.7 V			0.4	
		I _{OL} = 24 mA		3 V			0.55	
Ц		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ
loz‡		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ
ICC		$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			10	μΑ
ΔlCC		One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ
Ci	Control inputs	$V_I = V_{CC}$ or GND		3.3 V		4.5		pF
C _{io}	A or B ports	$V_O = V_{CC}$ or GND		3.3 V		11.5		pF

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} =		VCC =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
	(INPOT)	(001701)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	B or A	1.5	6	1	3.5		3.6	1.3	3.4	ns
t _{en}	ŌĒ	A or B	3.4	8.6	2	6		6.3	1.6	5.5	ns
^t dis	ŌĒ	A or B	2.7	8	1	4.8		5.3	1.7	5.5	ns

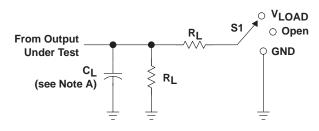
operating characteristics, $T_A = 25^{\circ}C$

ſ	PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	VCC = 3.3 V	UNIT	
L			TEST CONDITIONS	TYP	TYP	TYP	UNII	
ſ		Power dissipation capacitance	Outputs enabled	0 0 (40 M)	25	27	30	
L	C _{pd}	per transceiver	Outputs disabled	$C_L = 0$, $f = 10 MHz$	0	0	0	pF



 $^{^{\}dagger}$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ For I/O ports, the parameter I_{OZ} includes the input leakage current.

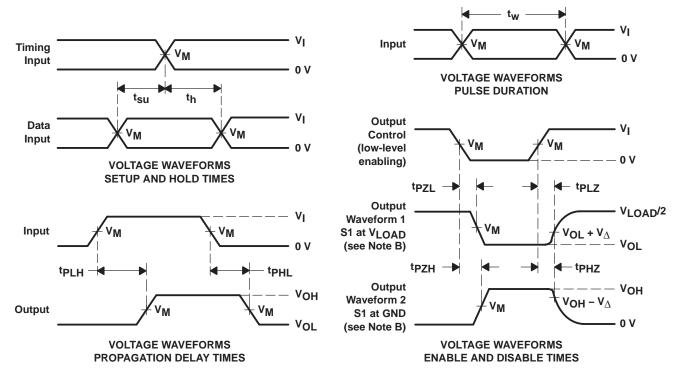
PARAMETER MEASUREMENT INFORMATION



TEST	S 1
t _{pd}	Open
t _{PLZ} /t _{PZL}	VLOAD
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

V	INPUT		V	V	C.	D.	V
Vcc	٧ _I	t _r /t _f	VΜ	VLOAD	CL	R_L	$v_{\scriptscriptstyle\Delta}$
1.8 V ± 0.15 V	vcc	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpzL and tpzH are the same as ten.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

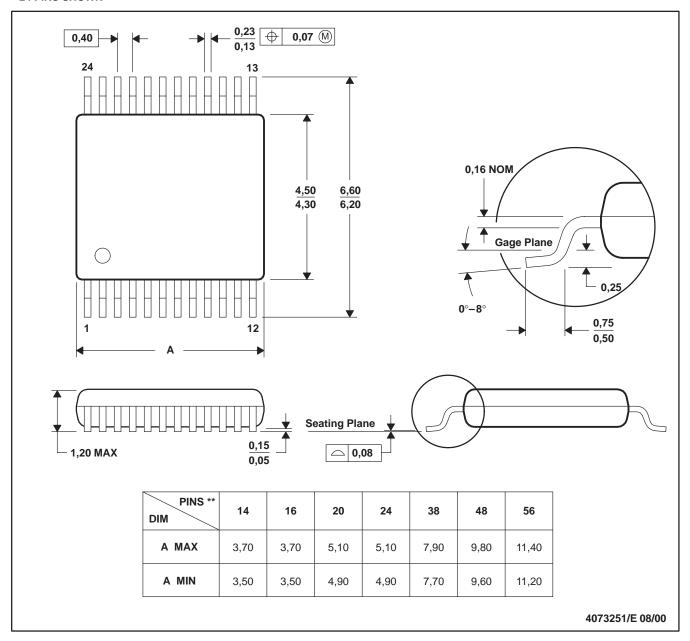
Figure 1. Load Circuit and Voltage Waveforms



DGV (R-PDSO-G**)

24 PINS SHOWN

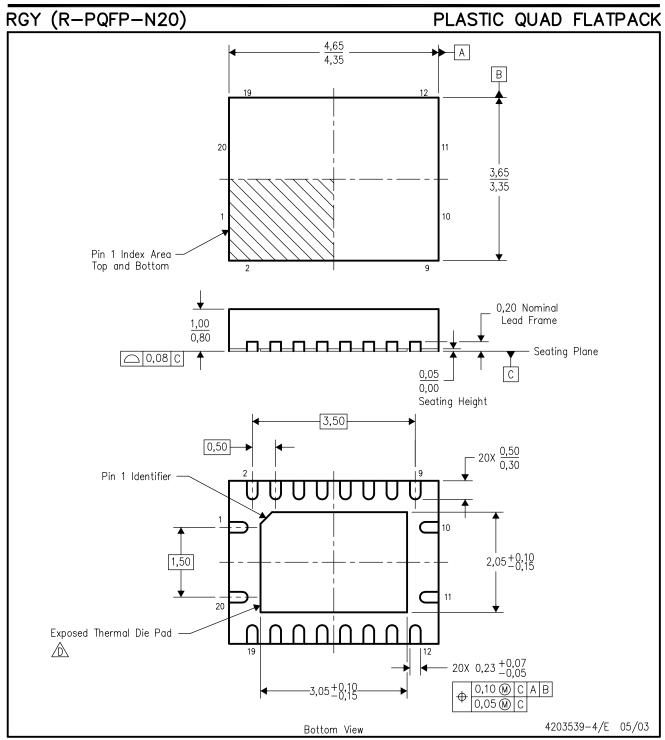
PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153 14/16/20/56 Pins – MO-194





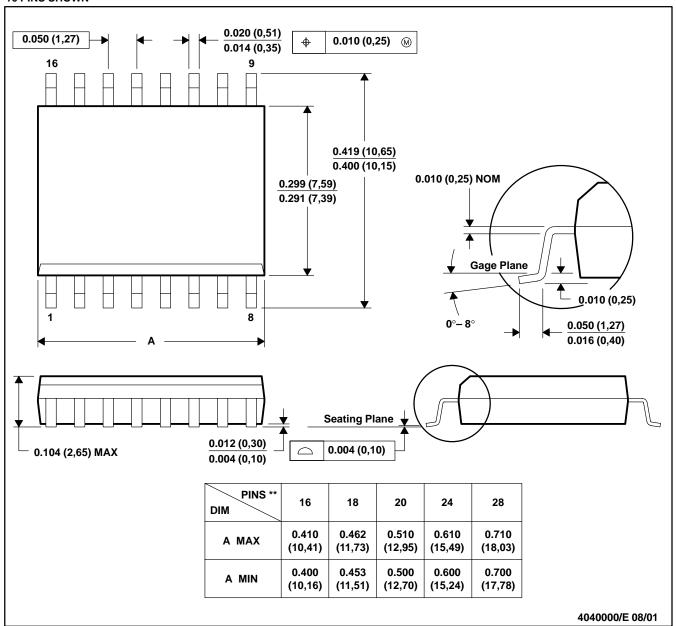
- NOTES: A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
 - E. Package complies to JEDEC MO-241 variation BC.



DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- . All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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